



Material Content Data Sheet



Sales Product Name	TLF50201EL			Issued	19. July 2018			
MA#	MA001056018							
Package	PG-SSOP-14-3			Weight*	82.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.797	2.17	2.17	21674	21674
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8309	
wire	non noble metal	copper	7440-50-8	27.978	33.74	34.62	337361	346189
	noble metal	gold	7440-57-5	0.114	0.14	0.14	1371	1371
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1204
encapsulation	plastics	epoxy resin	-	4.592	5.54		55370	
	inorganic material	silicondioxide	60676-86-0	45.220	54.51	60.17	545271	601845
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11770	11770
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9256	9256
glue	plastics	epoxy resin	-	0.164	0.20		1974	
	noble metal	silver	7440-22-4	0.491	0.59	0.79	5921	7895
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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